ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH BOND PAD AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: providing a semiconductor substrate; forming a core region on the semiconductor substrate with the core region having a core side; forming an inner bond pad on the semiconductor substrate with the inner bond pad having an inner core pad and an inner probe pad with the inner probe pad further from the core region than the inner core pad; and forming an outer bond pad on the semiconductor substrate and adjacent the inner bond pad with the outer bond pad having an outer core pad and an outer probe pad with the outer probe pad closer to the core region than the outer core pad, and the inner probe pad and the outer probe pad aligned parallel to the core side.

Fig. 1